

Announcement of the 61st Annual DEVICE RESEARCH CONFERENCE



University of Utah Salt Lake City, UT

June 23–25, 2003

CALL FOR PAPERS

Abstract Deadline: February 21, 2003 Late News Deadline: May 30, 2003

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The DRC brings together scientists, engineers, and students to discuss new and exciting breakthroughs and advances in the field of device research. DRC is sponsored by the IEEE, Electron Devices Society. The conference will be held at the University of Utah, Salt Lake City, Utah from Monday, June 23 through Wednesday, June 25, 2003.

DRC will be coordinated with the EMC (Electronic Materials Conference) during the same week, June 25–27, 2003, at the University of Utah, Salt Lake City, Utah. The coordinated efforts are made in recognition of the strong interaction between device research and electronic materials. This coordination provides for maximum exchange of information between attendees of both conferences. Inquiries about EMC should be forwarded to:

Prof. Ilesanmi Adesida Univ. of Illinois, Microelectronics Lab. 208 N. Wright St., Urbana, IL 61801 Tel: (217) 244-6379; Fax: (217) 244-6375 E-mail: adesida@capone.micro.uiuc.edu

Abstracts submitted to DRC may not be submitted to EMC.

PLENARY AND INVITED SESSIONS

Focussed sessions will be dedicated to new materials and technologies and novel devices in emerging areas of spin-based devices, carbon nanotubes, molecular devices, plastic electronics and nanofabrication technology. Invited speakers will present the latest development in these areas.

Partial List of Invited Speakers:

Joerg Appenzeller (İBM TJ Watson Res. Cntr.)

Robert Chau (Intel)

Steve Chou (Princeton University)
Russell Cowburn (University of Durham)
Tom Crowe (University of Virginia)
Hongjie Dai (Stanford University)

Dan Dapkus (University of Southern California)

Akira Endoh (Fujitsu)

Karl Hess (University of Illinois)

Bob Leheny (DARPA)

Klaus Ploog (Paul Drude Institute)

John Rogers (Lucent)

Sigurd Wagner (Princeton University)

BEST STUDENT PAPER AWARD

Papers presented by students, based on their own work, are eligible for this annual award. Please identify an abstract as a "Student Paper" in the cover letter when submitting.

POSTER AND DISCUSSION SESSIONS

Building on the success of the poster session in DRC 2002, abstracts will be accepted for an expanded session this year. Authors are encouraged to focus on exploratory device concepts, novel device technologies, and new results.

CALL FOR PAPERS

Authors are requested to send twenty-five (25) copies of a summary of their paper, together with the IEEE copyright transfer form found in the January issue of IEEE Journal, toPallabBhattacharya, University of Michigan, Dept. of Electrical Engineering and Computer Science, 1301 Beal Avenue, Ann Arbor, MI 48109-2122, USA. A summary sent electronically or by facsimile cannot be accepted. Authors should consult the DRC Web Pages for detailed instructions, http://www.tms.org/Meetings/Specialty/DRC/2003/DRC-2003-Home.html

ABSTRACT DEADLINE: February 21, 2003

PAPERS ARE SOLICITED ON A VARIETY OF NOVEL DEVICE STRUCTURES, BUT NOT LIMITED TO THE FOLLOWING:

- Spin-Based Devices
- Silicon CMOS/BiCMOS
- Carbon Nanotube and Molecular Devices
- Silicon Scaled and Ultrasmall Devices
- III-V FET & Bipolar Devices
- SOI & 3-D Devices
- Plastic Electronics
- Thin Insulators & Hot Electron Effects
- Millimeter Wave & Ultrafast Devices
- Non-Volatile, Static & Scaled Dynamic Memory
- Optical Sources & Detectors
- SiGe, SiGeC, & SiC Devices
- Integrated Optoelectronics
- High Voltage/High Power Devices
- Wide Bandgap Devices
- Device Modeling
- Sensors and Micromachined Devices
- Quantum Effect & Single Electron Devices
- Devices for Displays & Imaging
- Amorphous & Polycrystalline Devices
- Organic Emitters & Transistors
- Reliability
- Nanometer Device Technology
- Novel Magnetic Devices
- Superconducting Devices

FURTHER INFORMATION

Note: Registration and Housing information will be available in April 2003.

Early registration is encouraged with a reduced registration fee offered as an incentive. Students will also receive a reduced registration fee. Limited travel funds are available to students presenting papers. Further information on student assistance may be obtained by writing to Jeff Welser, General Program Chair (contact information listed in this brochure).

DEVICE
RESEARCH (DRC)
CONFERENCE CONFERENCE
JUNE 23–25, 2003 university of utah • salt lake city, utah
All prospective authors/attendees, please complete and return
 I plan to attend the conference. I wish to make a presentation at the conference and have enclosed an abstract. Please send me future announcements.
TITLE OF PRESENTATION:
AUTHORS NAMES & AFFILIATION:
NAME:
TITLE:
COMPANY, SCHOOL, OR ORGANIZATION:

ZIP:

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